



Hi-Rel SRAM MCPs

W X S XXX X XXX X V - XXX XXX X X X

**White Electronic Designs Corp.** \_\_\_\_\_

Blank= Multi-Chip Package \_\_\_\_\_

M = Monolithic \_\_\_\_\_

P = Plastic Multi-Chip Package \_\_\_\_\_

**SRAM** \_\_\_\_\_

**Number of Words** \_\_\_\_\_

**Word Factor** \_\_\_\_\_

K = Kilo \_\_\_\_\_

M = Mega \_\_\_\_\_

**Bits per Word** \_\_\_\_\_

**Improvement Mark** \_\_\_\_\_

B = BICMOS \_\_\_\_\_

L = Low Power for 2V Data Retention \_\_\_\_\_

N = No Connect for HIP only \_\_\_\_\_

**Voltage** \_\_\_\_\_

Blank = 5V Power Supply \_\_\_\_\_

V = 3.3V Power Supply \_\_\_\_\_

**Access Times (ns)** \_\_\_\_\_

**Package Type/Pin Configuration** \_\_\_\_\_

B = 143 PBGA	G1U = 68 CQFP (0.94" sq., 0.140" high)
C = 32 DIP	G2S = 68 CQFP (0.88" sq., 0.300" high)
CL = 32 CLCC	G2T = 68 CQFP (0.88" sq., 0.180" high)
DE = 32 SOJ (Evol.)	G3 = 84 CQFP (1.07" sq., 0.169" high)
DR = 32 SOJ (Revol.)	G4 = 68 CQFP (1.56" sq., 0.200" high)
DJ = 36 SOJ	G4T = 68 CQFP (1.56" sq., 0.140" high)
DL = 44 SOJ	G4W = 116 CQFP (1.56" sq., 0.200" high)
FE = 32 Flatpack (Evol.)	H = 66 PGA (HIP), (1.185" sq.)
FR = 32 Flatpack (Revol.)	H1 = 66 PGA (HIP), (1.075" sq.)
F = 36 Flatpack w/Tie Bar	H2 = 66 PGA (HIP), (1.385" sq.)
FL = 44 Flatpack	
FG = 44 Flatpack, Lead Formed	
G1T = 68 CQFP (0.94" sq., 0.140" high)	

**Device Grade** \_\_\_\_\_

Q = MIL-PRF-38534 Compliant \_\_\_\_\_

M = Military, screened \_\_\_\_\_ -55°C to +125°C

I = Industrial \_\_\_\_\_ -40°C to +85°C

C = Commercial \_\_\_\_\_ 0°C to +70°C

**Special Processing** \_\_\_\_\_

E = Epitaxial Layer \_\_\_\_\_

**Lead Finish** \_\_\_\_\_

Blank= Gold plated leads \_\_\_\_\_

A = Solder Dip leads \_\_\_\_\_

Note: Not all packages, speeds and other options are available on every product. Please refer to the individual data sheet for option selection.